Rochester Electronics

Datasheet

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FAIRCHILD SEMICONDUCTOR®

November 1988
Revised February 2005

74AC11
Triple 3-Input AND Gate

General Description

The AC11 contains three 3-input AND gates.

Features

- I_{CC} reduced by 50%
- Outputs source/sink 24 mA

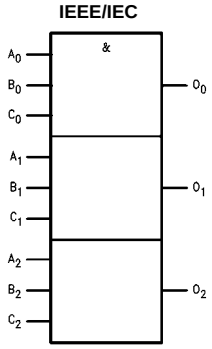
Ordering Code:

Order Number	Package Number	Package Description
74AC11SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74AC11SJ	M14D	Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC11MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC11MTCX_NL (Note 1)	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC11PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

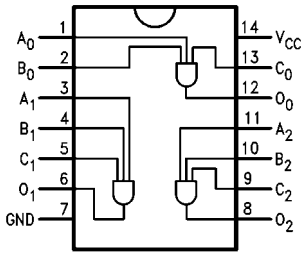
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

Note 1: "_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Device available in Tape and Reel only.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description
A_n, B_n, C_n	Inputs
O_n	Outputs

FACT™ is a trademark of Fairchild Semiconductor Corporation.

Absolute Maximum Ratings(Note 2)

Supply Voltage (V_{CC})	−0.5V to +7.0V
DC Input Diode Current (I_{IK})	
V_I = −0.5V	−20 mA
V_I = V_{CC} + 0.5V	+20 mA
DC Input Voltage (V_I)	−0.5V to V_{CC} + 0.5V
DC Output Diode Current (I_{OK})	
V_O = −0.5V	−20 mA
V_O = V_{CC} + 0.5V	+20 mA
DC Output Voltage (V_O)	−0.5V to V_{CC} + 0.5V
DC Output Source	
or Sink Current (I_O)	± 50 mA
DC V_{CC} or Ground Current	
per Output Pin (I_{CC} or I_{GND})	± 50 mA
Storage Temperature (T_{STG})	−65°C to +150°C
Junction Temperature (T_J)	
PDIP	140°C

Recommended Operating Conditions

Supply Voltage (V_{CC})	2.0V to 6.0V
Input Voltage (V_I)	0V to V_{CC}
Output Voltage (V_O)	0V to V_{CC}
Operating Temperature (T_A)	−40°C to +85°C
Minimum Input Edge Rate ($\Delta V/\Delta t$)	125 mV/ns
V_{IN} from 30% to 70% of V_{CC}	
V_{CC} @ 3.3V, 4.5V, 5.5V	

Note 2: Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation of FACT™ circuits outside databook specifications.

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	T_A = +25°C Typ	T_A = −40°C to +85°C Guaranteed Limits		Units	Conditions
V_{IH}	Minimum HIGH Level	3.0	1.5	2.1	2.1		V_{OUT} = 0.1V
	Input Voltage	4.5	2.25	3.15	3.15	V	or V_{CC} − 0.1V
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum LOW Level	3.0	1.5	0.9	0.9		V_{OUT} = 0.1V
	Input Voltage	4.5	2.25	1.35	1.35	V	or V_{CC} − 0.1V
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum HIGH Level	3.0	2.99	2.9	2.9		
	Output Voltage	4.5	4.49	4.4	4.4	V	I_{OUT} = −50 μA
		5.5	5.49	5.4	5.4		
							V_{IN} = V_{IL} or V_{IH}
		3.0		2.56	2.46		I_{OH} = −12 mA
		4.5		3.86	3.76	V	I_{OH} = −24 mA
		5.5		4.86	4.76		I_{OH} = −24 mA (Note 3)
V_{OL}	Maximum LOW Level	3.0	0.002	0.1	0.1		
	Output Voltage	4.5	0.001	0.1	0.1	V	I_{OUT} = 50 μA
		5.5	0.001	0.1	0.1		
							V_{IN} = V_{IL} or V_{IH}
		3.0		0.36	0.44		I_{OL} = 12 mA
		4.5		0.36	0.44	V	I_{OL} = 24 mA
		5.5		0.36	0.44		I_{OL} = 24 mA (Note 3)
I_{IN} (Note 5)	Maximum Input Leakage Current	5.5		± 0.1	± 1.0	μA	V_I = V_{CC}, GND
I_{OLD}	Minimum Dynamic	5.5			75	mA	V_{OLD} = 1.65V Max
I_{OHD}	Output Current (Note 4)	5.5			−75	mA	V_{OHD} = 3.85V Min
I_{CC} (Note 5)	Maximum Quiescent Supply Current	5.5		2.0	20.0	μA	V_{IN} = V_{CC} or GND

Note 3: All outputs loaded; thresholds on input associated with output under test.

Note 4: Maximum test duration 2.0 ms, one output loaded at a time.

Note 5: I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC}.

AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V) (Note 6)	$T_A = +25°C$, $C_L = 50$ pF			$T_A = -40°C$ to $+85°C$, $C_L = 50$ pF		Units
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	3.3	1.5	5.5	9.5	1.0	10.0	ns
		5.0	1.5	4.0	8.0	1.0	8.5	
t_{PHL}	Propagation Delay	3.3	1.5	5.5	8.5	1.0	9.5	ns
		5.0	1.5	4.0	7.0	1.0	7.5	

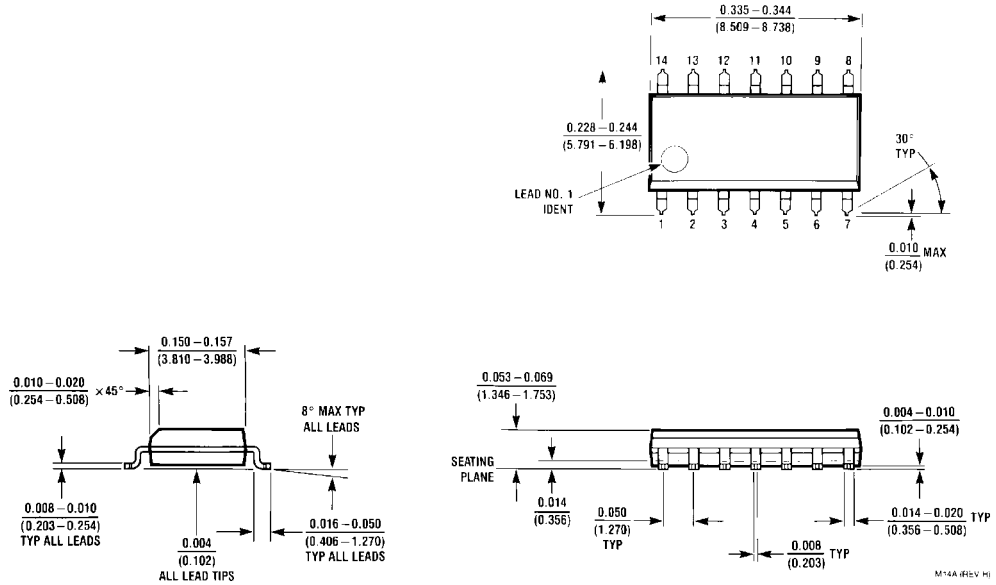
Note 6: Voltage Range 3.3 is 3.3V ± 0.3V

Voltage Range 5.0 is 5.0V ± 0.5V

Capacitance

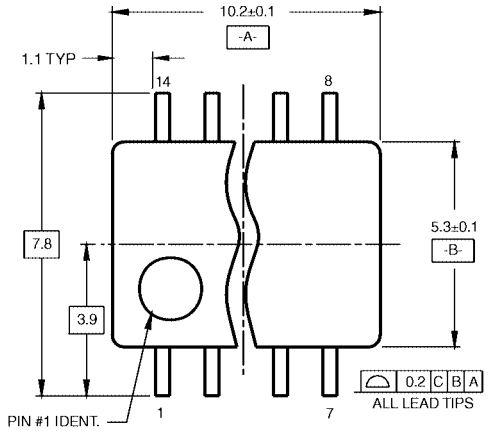
Symbol	Parameter	Typ	Units	Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = OPEN
C_{PD}	Power Dissipation Capacitance	20.0	pF	V_{CC} = 5.0V

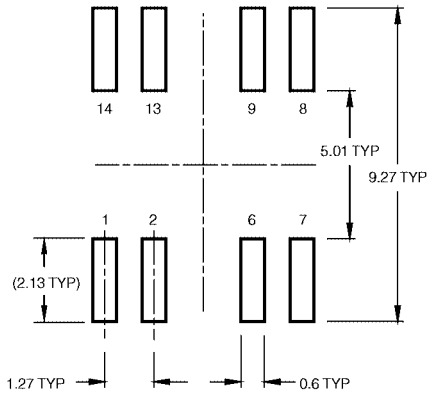
Physical Dimensions inches (millimeters) unless otherwise noted



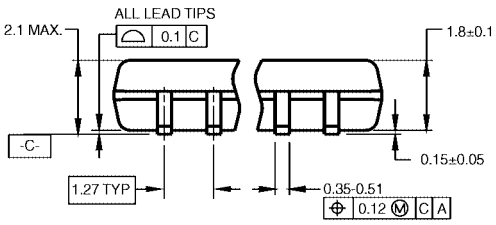
14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M14A

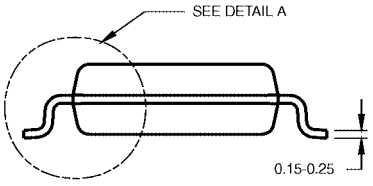
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



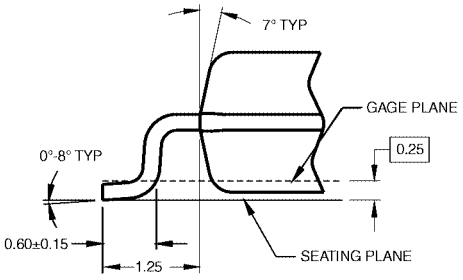


LAND PATTERN RECOMMENDATION





DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

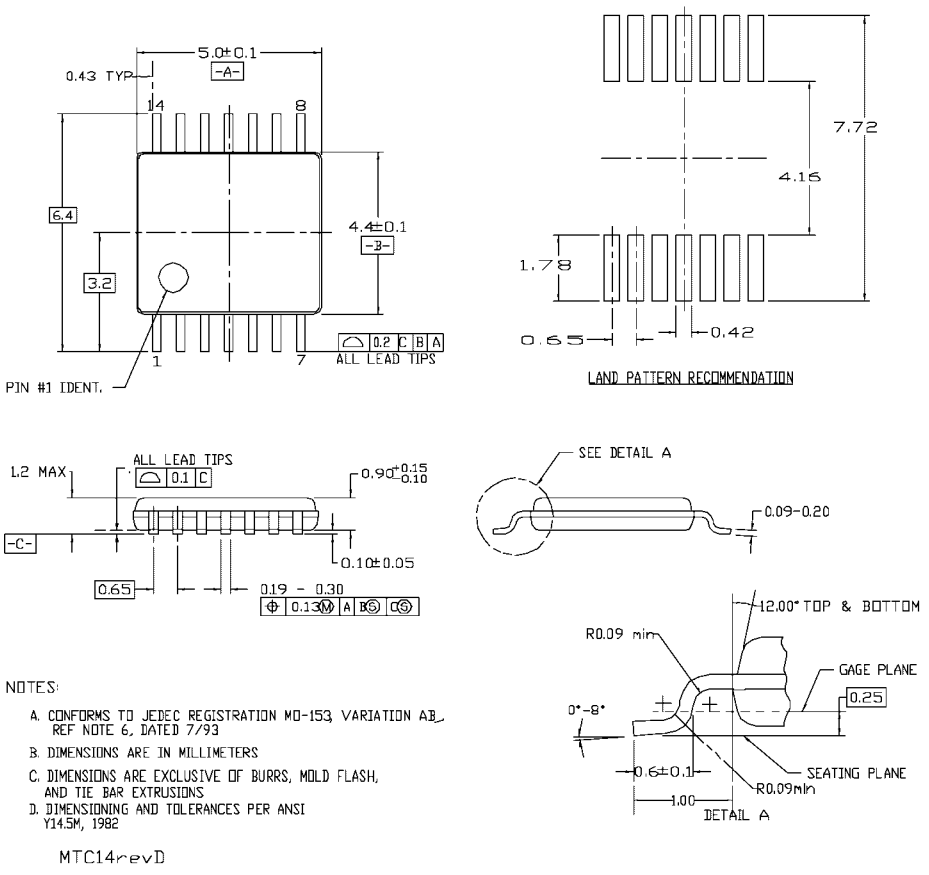
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATED 7/93

B. DIMENSIONS ARE IN MILLIMETERS

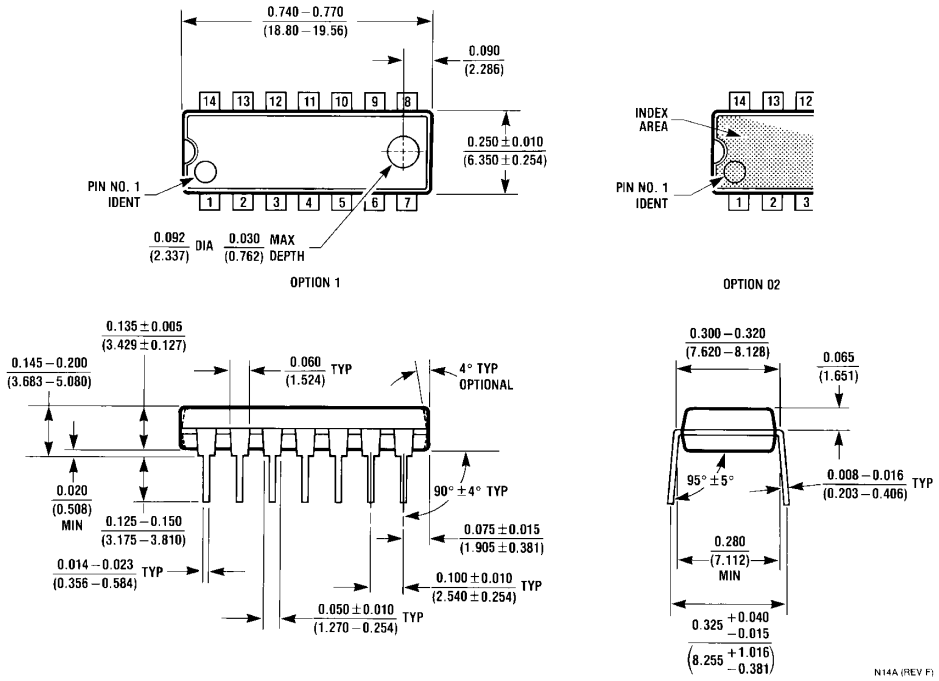
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD

14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N14A